Optically Immersed 5.5 μm LED in heatsink optimized housing

LED55 Sr/Su/Cy

TE cooled Optically Immersed 5.5 μm LED
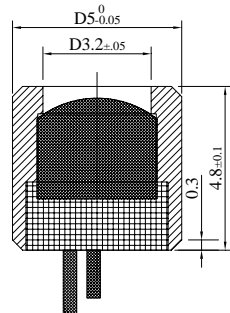
LED55TO8TEC

Peak wavelength	μm		5.5÷5.6		@22 °C
				LED55Sr/Su/Cy	LED55TO8TEC
Pulse power	μW	Drive current 1 A, 0.02 duty cycle	5÷7		4÷5.6
Quasi-CW power	μW	Drive current 0.3 A, 0.5 duty cycle	2.2÷2.7		1.8÷2.2
CW power	μW	Drive current 0.2 A	1.5÷1.8		1.2÷1.4
Cut-off frequency	MHz		50 [1]		

Code	Emission size, mm	Weight, g	Optical components	Far-field pattern FWHM, deg.	Optical axis deviation, deg.	Optical power deviation in lot, %	Operation conditions, °C	Lifetime, hrs
LED55 Sr/Su/Cy	∅ 3.2	~0.4	Si lens	~15	≤5	±25	-60÷+85	>100 000
LED55 TO8TEC		~10	Si lens and output sapphire window D=6mm					

Product view

LED55Cy

D5 0/-0.05
D3.2 ±.05
4.8±0.1
0.3

Pin assignment: red wire or long wire and red point on house - positive

LED55Sr

M5*0.5
D 3.2
0.5
4.8
0.5

Pin assignment: red wire or long wire and red point on house - positive

D15.4±0.1
D6
2.5
10.5±0.1
7.8
6.4
D0.45
thread 4-40 UNC

Lens
LED chip
TEC
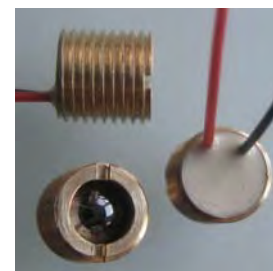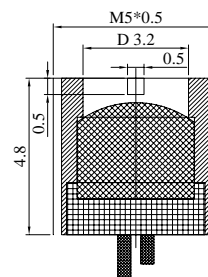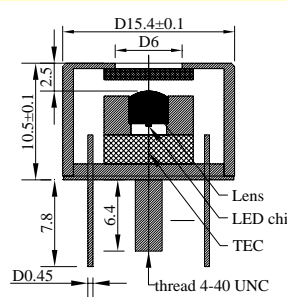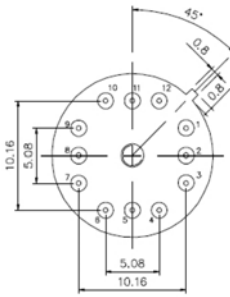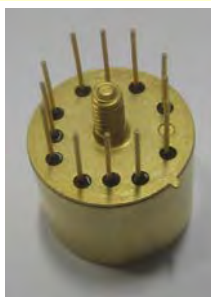
Pin assignment LED55TO8TEC12

1 TEC negative;
3 TEC positive;
4 LED negative;
6 LED pozitive;
7, 9 thermosensor;
11 ⊥ (House)

Features

- Original growth of narrow gap semiconductor alloys onto n⁺-InAs substrate;
- Flip-chip design of LEDs;
- Optical coupling through the use of chalcogenide glasses and Si lenses with antireflection coating

- 3-fold increased LED output power;
- Beam collimation;
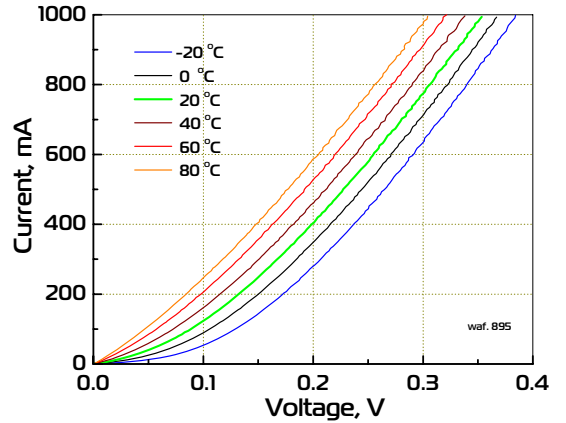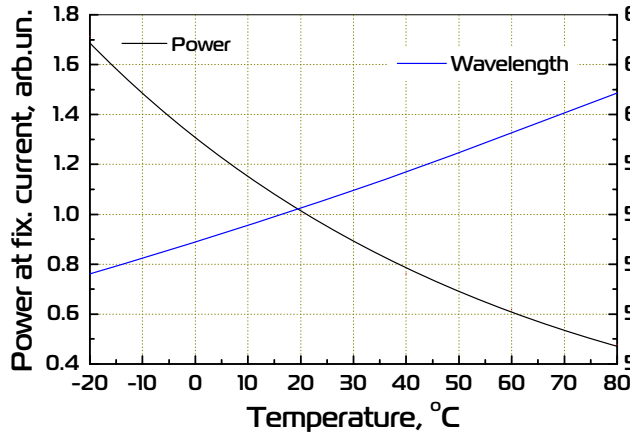- Small on-off time (tenths of ns);
- Low power consumption (≤0.1 W)

Emission beam divergence is small and thus we recommend adjusting LED position regarding to the detector system before final evaluation/use of the devices. We recommend if possible using low duty cycle mode of operation with I<0.5×Imax so that higher efficiency and long term stability of a LED are achieved. Data are valid for LED attached to a heatsink and thermostabilized at 22°C. Heatsink is essential for TEC operation!

Notes

[1] – according to estimation

Product specifications are subject to change without prior notice due to improvements or other reasons. Updated 20.01.15

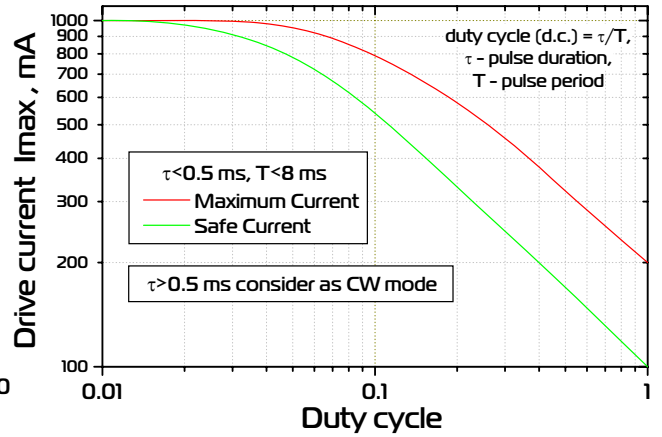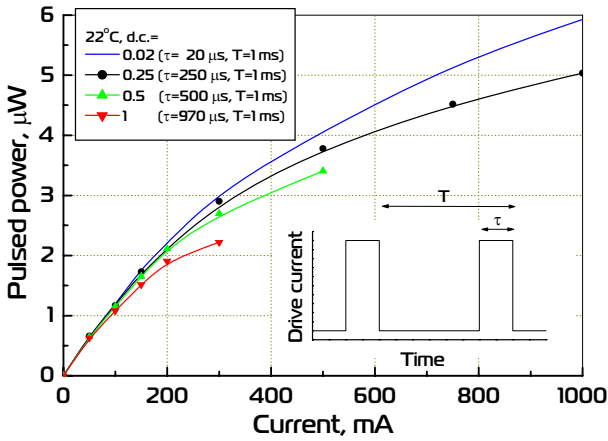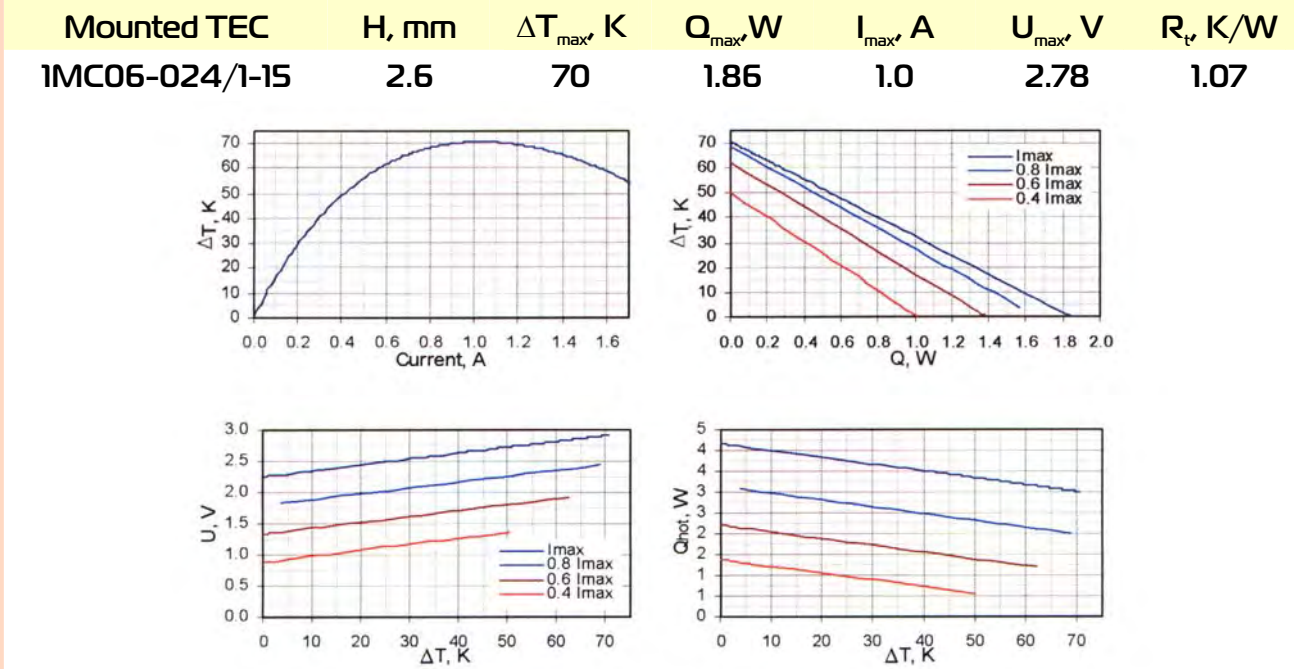**Emission spectra**
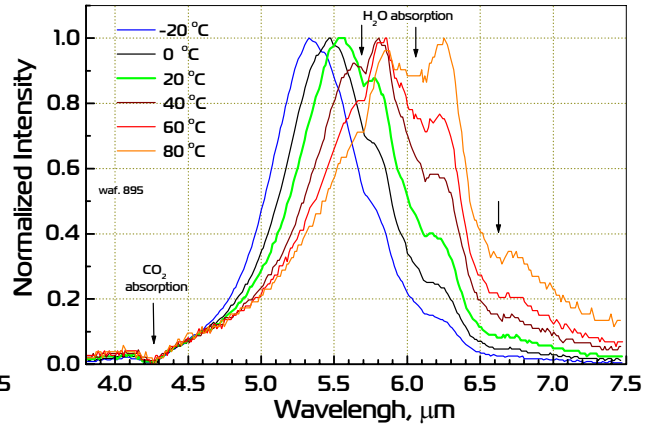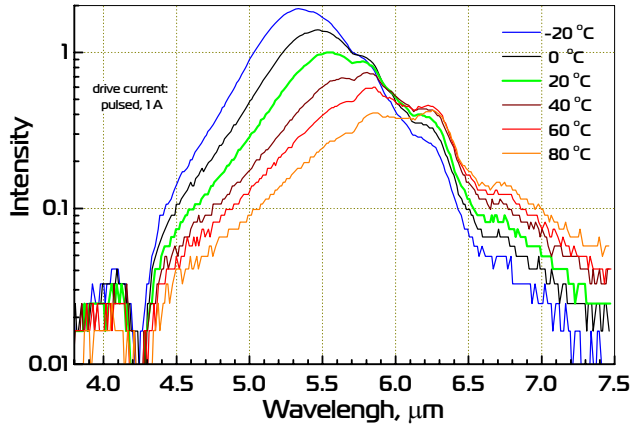
Power and peak wavelength vs. temperature; I – V curves

Output power and drive current vs operation conditions

BostonElectronics   **www.boselec.com** | **boselec@boselec.com** | **617-566-3821**

Thermoelectric cooling module datasheet

Mounted TEC	H, mm	ΔT_{max}, K	Q_{max}, W	I_{max}, A	U_{max}, V	R_t, K/W
1MC06-024/1-15	2.6	70	1.86	1.0	2.78	1.07

Data for T_{hot}=300 K, from www.tec-microsystems.com; www.rmtltd.ru

Thermistor specification

Type TB04-103

T, °C	R, kΩ	T, °C	R, kΩ
-60	1134.5	15	12.44
-55	762.4	20	10.00
-50	521.6	25	8.09
-45	362.8	25	8.09
-40	256.3	30	6.60
-35	183.8	35	5.41
-30	133.6	40	4.47
-25	98.3	45	3.71
-20	73.3	50	3.10
-15	55.2	55	2.61
-10	42.1	60	2.20
-5	32.4	65	1.87
0	25.2	70	1.59
5	19.7	75	1.37
10	15.6	80	1.18

Termistor calibration

$R_t = R_{to} \exp(\beta(T_0-T)/(T*T_0))$, where
R_{to} - Resistivity at standard temperature (T_0=293K),
β =3691 K - Beta constant
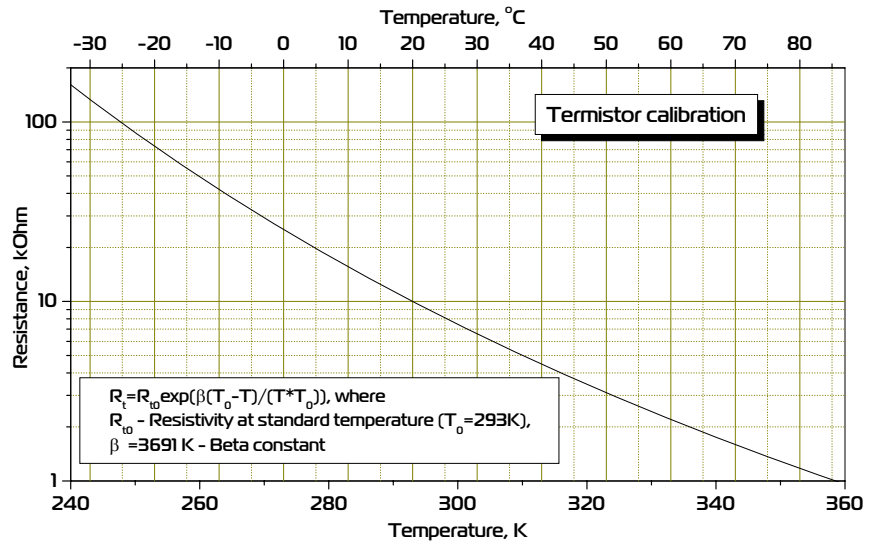
Possible TEC heatsink view